**TENTATIVE** 

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSVI)

# 2SK3567

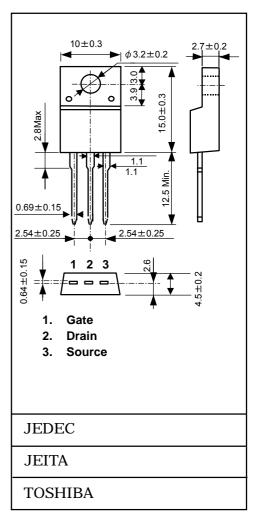
unit: mm

### **Switching Regulator Applications**

- Low drain-source ON resistance: RDS (ON) = 1.7 (typ.)
- High forward transfer admittance:  $|Y_{fs}| = S$  (typ.)
- Low leakage current:  $IDSS = 100 \mu A (VDS = 600 V)$
- Enhancement-mode:  $V_{th} = 2.0 \sim 4.0 \text{ V}$  ( $V_{DS} = 10 \text{ V}$ ,  $I_D = 1 \text{ mA}$ )

### **Maximum Ratings (Ta = 25°C)**

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	600	V	
Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ )		$V_{DGR}$	600	V	
Gate-source voltage		$V_{GSS}$	±30	V	
Drain current	DC (Note 1)	I <sub>D</sub>	3.5	Α	
	Pulse (t = 1 ms) (Note 1)	I <sub>DP</sub>	14		
Drain power dissipati	on (Tc = 25°C)	P <sub>D</sub>	35	W	
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	TBD	mJ	
Avalanche current		I <sub>AR</sub>	3.5	Α	
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	3.5	mJ	
Channel temperature	)	T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	



#### **Thermal Characteristics**

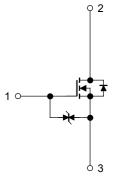
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	3.57	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	62.5	°C/W

Note 1: Please use devices on conditions that the channel temperature is below 150°C.

Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C, L = TBD mH,  $I_{AR}$  = 3.5 A,  $R_G$  = 25  $\Omega$ 

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device. Please handle with caution.



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## Electrical Characteristics (Ta = 25°C)

Chara	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I <sub>GSS</sub>	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Gate-source brea	kdown voltage	V (BR) GSS	$I_G = \pm 10 \ \mu A, \ V_{GS} = 0 \ V$	±30	_	_	V
Drain cut-off curre	ent	I <sub>DSS</sub>	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V	_	_	100	μΑ
Drain-source brea	akdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	600	_	_	V
Gate threshold vo	oltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	V
Drain-source ON	resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1.8 A	_	1.7	2.2	Ω
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 1.8 A	TBD	TBD	_	S
Input capacitance		C <sub>iss</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	TBD	_	pF
Reverse transfer capacitance		C <sub>rss</sub>		_	TBD	_	
Output capacitance		C <sub>oss</sub>			TBD		
Switching time	Rise time	t <sub>r</sub>	$\begin{array}{c c} 10 \text{ V} & I_D = 1.8 \text{A} & V_{OUT} \\ V_{GS} & & & \\ 0 \text{ V} & & & \\ 4.7 \Omega & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & $	_	TBD	_	
	Turn-on time	t <sub>on</sub>			TBD		ne
	Fall time	t <sub>f</sub>			TBD		ns
	Turn-off time	t <sub>off</sub>	Duty ≦ 1%, t <sub>W</sub> = 10 μs	_	TBD	_	
Total gate charge		Qg		_	TBD	_	
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \simeq 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3.5 \text{ A}$	_	TBD	_	nC
Gate-drain charge		Q <sub>gd</sub>		_	TBD		

## Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	3.5	А
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	14	Α
Forward voltage (diode)	V <sub>DSF</sub>	$I_{DR} = 3.5 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.9	V
Reverse recovery time	t <sub>rr</sub>	$I_{DR} = 3.5 \text{ A}, V_{GS} = 0 \text{ V},$	_	TBD	_	ns
Reverse recovery charge	Q <sub>rr</sub>	dI <sub>DR</sub> /dt = 100 A/μs	_	TBD	_	μС

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